


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	ADG/23/13978	
1.3 Title of PCN	DPAK new Lead Frame design-Tongfu Microelectronics (TFME) - INDUSTRIAL	
1.4 Product Category	Power MOSFET	
1.5 Issue date	2023-03-17	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	KRISZTINA NEMETH
2.1.2 Phone	+49 89460062210
2.1.3 Email	krisztina.nemeth@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Maurizio GIUDICE
2.1.2 Marketing Manager	Anna MOTTESE
2.1.3 Quality Manager	Vincenzo MILITANO

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	New direct material part number (same supplier, different supplier or new supplier), Lead frame base material	Tongfu Microelectronics (TFME)

4. Description of change

	Old	New
4.1 Description	DPAK Industrial package produced in Tongfu Microelectronics (TFME), is manufactured with Standard Die Pad lead frame	DPAK Industrial package produced in Tongfu Microelectronics (TFME), is manufactured with Large Die Pad lead frame
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	processability	

5. Reason / motivation for change

5.1 Motivation	PRODUCTION IMPROVEMENT
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	By internal traceability and dedicated FG code.
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7. Timing / schedule

7.1 Date of qualification results	2023-03-02
7.2 Intended start of delivery	2023-06-02
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	13978 Binder1.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2023-03-17

9. Attachments (additional documentations)

13978 Public product.pdf
 13978 13978 - DPAK New lead frame design - TFME - INDUSTRIAL.pdf
 13978 Binder1.pdf
 13978 Comparison DPAK TFME C2 vs C3.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STD10NM60N	
	STD13N60M2	
	STD13NM60N	
	STD13NM60ND	
	STD16N50M2	
	STD16N60M2	
	STD16N65M5	
	STD16NF25	
	STD17NF25	
	STD18N55M5	
	STD18N60M6	
	STD18N65M5	
	STD3NK100Z	
	STD4N62K3	
	STD5N52K3	
	STD5N62K3	
	STD5N95K5	
	STD6N62K3	
	STD6N90K5	
	STD6N95K5	
	STD7N52K3	
	STD7N80K5	
	STD8N80K5	
	STGD4M65DF2	
	STGD5H60DF	
	STGD8NC60KDT4	
MJD44H11T4	MJD44H11T4	
MJD45H11T4	MJD45H11T4	
	STD15N65M5	
STD2NK90ZT4	STD2NK90ZT4	
STD3NK80ZT4	STD3NK80ZT4	
STD3NK90ZT4	STD3NK90ZT4	
STD4NK60ZT4	STD4NK60ZT4	
STD4NK80ZT4	STD4NK80ZT4	
STD5NK60ZT4	STD5NK60ZT4	
	STGD6NC60HDT4	

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